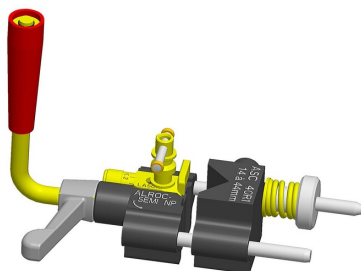




See online
technical sheet

/ ASC 40R1

Tools for bonded semiconductor and chamfer



/ Use

ASC tools allow the removal of the non-peelable semiconductor with the creation of a chamfer and a very correct surface finish.

/ Advantages

- Robust design
- Lightweight
- Easy to get to grips with

/ Technical specifications

- Specific tools : Cable tools
- Cable tools : Cable tools
- For network cables : HTA
- Packaging : Carton box
- Max diameter (mm) : 40
- Mini diameter (mm) : 14
- Incision depth on semi-peelable material : 0,1 à 1,4 mm
- Weight (g) : 650

/ Spare parts

	Reference	Designation
	LASCRT	Blade for bonded semiconductor